

Title (en)

Mould and method of production of a mould

Title (de)

Verfahren zur Herstellung eines Kokillenkörpers und Kokillenkörper

Title (fr)

Lingotière pour la coulée continue et procédé de sa fabrication

Publication

EP 0924010 B1 20020904 (DE)

Application

EP 98123408 A 19981209

Priority

DE 19756164 A 19971217

Abstract (en)

[origin: EP0924010A1] The mold structure is solid-solution annealed, the wear resistant layer is produced on the mold structure and the mold structure is hardened. The hardness of the wear resistant layer (7) of the mold decreases with the distance from the layer surface (8) towards the mold structure (5). The method for producing a mold with a mold structure (1) consisting of a hardenable copper alloy, and an interior wear resistant layer (7) consisting of chromium involves the following steps: a) the mold structure is solid-solution annealed; b) the wear resistant layer is produced on the mold structure; c) the mold structure is hardened. The hardness of the wear resistant layer (7) of the mold decreases with the distance from the layer surface (8) towards the mold structure (5).

IPC 1-7

B22D 11/04

IPC 8 full level

B22D 11/04 (2006.01); **B22D 7/06** (2006.01); **B22D 11/059** (2006.01); **C23C 24/00** (2006.01)

CPC (source: EP KR US)

B22D 11/004 (2013.01 - KR); **B22D 11/0408** (2013.01 - KR); **B22D 11/059** (2013.01 - EP KR US); **B22D 27/003** (2013.01 - KR); **C22C 9/00** (2013.01 - KR); **Y10T 428/12847** (2015.01 - EP US); **Y10T 428/12903** (2015.01 - EP US)

Cited by

AT500814A1; AT500814B1; DE102010012309A1; WO2008049081A1

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

EP 0924010 A1 19990623; **EP 0924010 B1 20020904**; AR 009930 A1 20000503; AT E223267 T1 20020915; AU 744465 B2 20020221; AU 9712898 A 19990708; BR 9805419 A 19991109; CA 2256207 A1 19990617; CA 2256207 C 20050329; CN 1095708 C 20021211; CN 1220924 A 19990630; CZ 415698 A3 19991013; DE 19756164 A1 19990624; DE 59805400 D1 20021010; DK 0924010 T3 20030106; ES 2180114 T3 20030201; JP H11244997 A 19990914; KR 19990062793 A 19990726; PL 330305 A1 19990621; PT 924010 E 20030131; RU 2211111 C2 20030827; TW 396072 B 20000701; US 2001006738 A1 20010705; US 6206987 B1 20010327; US 6383663 B2 20020507; ZA 9811283 B 19990614

DOCDB simple family (application)

EP 98123408 A 19981209; AR P980106380 A 19981215; AT 98123408 T 19981209; AU 9712898 A 19981216; BR 9805419 A 19981217; CA 2256207 A 19981215; CN 98125572 A 19981217; CZ 415698 A 19981216; DE 19756164 A 19971217; DE 59805400 T 19981209; DK 98123408 T 19981209; ES 98123408 T 19981209; JP 35665698 A 19981215; KR 19980053022 A 19981204; PL 33030598 A 19981215; PT 98123408 T 19981209; RU 98122843 A 19981216; TW 87121062 A 19981217; US 21307498 A 19981216; US 77084201 A 20010126; ZA 9811283 A 19981209